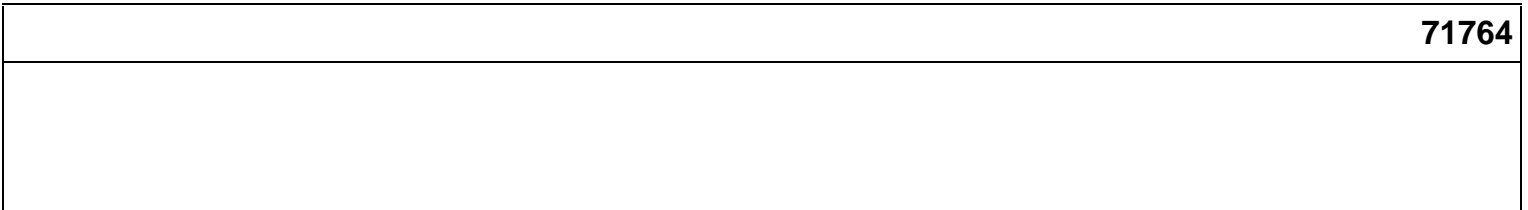


CKTS	DIM. A	DIM. B
04	(5.08)/.200	(2.54)/.100
06	(7.62)/.300	(5.08)/.200
08	(10.16)/.400	(7.62)/.300
10	(12.70)/.500	(10.16)/.400
12	(15.24)/.600	(12.70)/.500
14	(17.78)/.700	(15.24)/.600
16	(20.32)/.800	(17.78)/.700
18	(22.86)/.900	(20.32)/.800
20	(25.40)/1.000	(22.86)/.900
22	(27.94)/1.100	(25.40)/1.000
24	(30.48)/1.200	(27.94)/1.100
26	(33.02)/1.300	(30.48)/1.200
28	(35.56)/1.400	(33.02)/1.300
30	(38.10)/1.500	(35.56)/1.400

- NOTES:
- MATERIAL: WAFER - HIGH TEMPERATURE THERMAL PLASTIC, 94V-0, COLOR: BLACK
PIN - COPPER ALLOY
 - PLATING:
TIN - (0.00381)/.000150 MINIMUM TIN PLATE OVER NICKEL PLATE.
15 GOLD - (0.000381)/.000015 MINIMUM GOLD PLATE IN SELECT AREA, (0.00191)/.000075 MINIMUM TIN PLATE IN SELECT AREA, OVER NICKEL PLATE OVERALL.
30 GOLD - (0.00076)/.000030 MINIMUM GOLD PLATE IN SELECT AREA, (0.00191)/.000075 MINIMUM TIN PLATE IN SELECT AREA, OVER NICKEL PLATE OVERALL.
 - * THE PRIMARY SHIPPING CARTON WILL BE LABELD 'COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC'. CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.
 - PRODUCT CONFORMS TO PS-71764.
 - PACKAGING INFORMATION:
FOR 4 THRU 8 CIRCUIT PARTS USE PK-70873-0353
FOR 10 CIRCUITS AND OVER USE PK-70873-0075
 - FOR ILLUSTRATION PURPOSES, 20 (DUAL 10) CIRCUIT SIZE IS SHOWN.
 - PINS MUST MEET SOLDERABILITY SPEC. ES-152, EXCEPT VOIDS ARE PERMISSIBLE AT BANDOLIER PIN AT BANDOLIER PIN FAYING SURFACE. (APPROX. (0.64)/.025 LNG X (0.15)/.006 WD. REF.) 2 LOCATIONS
 - WAFER TO BE FLAT WITHIN (0.03 MM/CM) OR .003 IN./IN
 - MEASURE POINT FOR PLATING THICKNESS.
 - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002

ADD NOTE 9 EC NO. UCP2007-1441 DRAWN BY: 2006/12/11 CHKD BY: 2006/12/11 APPROV: SMITH 2006/12/12	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION
		4 PLACES ± --- ± ---	3 PLACES ± --- ± .01	2 PLACES ± 0.25 ± .01	1 PLACE ± 0.25 ± ---	ANGULAR ±1/2°	DRAWN BY: CAC DATE: 1995/08/23	CHECKED BY: PR DATE: 1995/08/23
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		MATERIAL NO. SD-71764-001		DOCUMENT NO. SD-71764-001		SHEET NO. 1 OF *
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

2	A
1	A1
SHT. REV.	



ITEM NO: 71764-0004/0030, 9003				ITEM NO: 71764-0104/0130, 9001, 9004				ITEM NO: 71764-0204/0230, 9000, 9002			
DIM. C		(6.10)/.240		DIM. C		(6.10)/.240		DIM. C		(6.10)/.240	
DIM. E (REF.)		(2.79)/.110		DIM. E (REF.)		(2.79)/.110		DIM. E (REF.)		(2.79)/.110	
FINISH		TIN		FINISH		15 GOLD		PLATING FINISH		30 GOLD	
CONNECTOR END PLATING		TIN		CONNECTOR END PLATING		GOLD		CONNECTOR END PLATING		GOLD	
P.C. BOARD END PLATING		TIN		P.C. BOARD END PLATING		TIN		P.C. BOARD END PLATING		TIN	
PACKAGING		SEE NOTE 4 SHEET 1		PACKAGING		SEE NOTE 4 SHEET 1		PACKAGING		SEE NOTE 4 SHEET 1	
CKTS	ITEM NUMBER	VOIDS		CKTS	ITEM NUMBER	VOIDS		CKTS	ITEM NUMBER	VOIDS	
04	71764-0004			04	71764-0104			04	71764-0204		
06	71764-0006			06	71764-0106			06	71764-0206		
08	71764-0008			08	71764-0108			08	71764-0208		
10	71764-0010			10	71764-0110			10	71764-0210		
12	71764-0012			12	71764-0112			12	71764-0212		
14	71764-0014			14	71764-0114			14	71764-0214		
16	71764-0016			16	71764-0116			16	71764-0216		
18	71764-0018			18	71764-0118			18	71764-0218		
20	71764-0020			20	71764-0120			20	71764-0220		
22	71764-0022			22	71764-0122			22	71764-0222		
24	71764-0024			24	71764-0124			24	71764-0224		
26	71764-0026			26	71764-0126			26	71764-0226		
28	71764-0028			28	71764-0128			28	71764-0228		
30	71764-0030			30	71764-0130			30	71764-0230		
06	71764-9003	3		06	71764-9001	3, 4		06	71764-9002	3, 4	
				08	71764-9004	5, 6					
								10	71764-9000	8	

A	REV: ECR/ECN INFORMATION	TITLE: DUAL ROW WAFER ASS'Y W/ BREAK-OFF OPTION RT. ANG. (0.64)/.025 SQ PINS	SHEET No. - 2 -
	EC No: UCP2007-0449		
	DATE: 2006-08-18		
DOCUMENT NUMBER: SD-71764-001	CREATED / REVISED BY: PRIDDER	CHECKED BY: ADERR	APPROVED BY: FSMITH

